Golden Award IC & Components

Intel® Core™ Ultra系列3處理器 /
Intel® Core™ Ultra processor

Intel Corporation
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Winning Reason

The Intel® Core™ Ultra processor Series 3 (Panther Lake) leverages the advanced Intel 18A process node, introducing the pioneering RibbonFET transistor architecture and PowerVia backside power delivery technology. By utilizing cutting-edge advanced packaging and 3D silicon stacking, multiple compute tiles are integrated into a single SoC, significantly enhancing the synergy between CPU, GPU, and NPU. This architecture delivers superior performance in high-performance computing, graphics processing, and AI inference while substantially reducing power consumption compared to its predecessor. Designed to expand into diverse edge computing scenarios—including robotics, smart cities, automation, and healthcare—this processor is poised for widespread adoption across PCs, laptops, and edge devices, exerting immense market influence.

Product Feature

Intel® Core™ Ultra Series 3 processors, the first compute platform built on Intel 18A - the most advanced semiconductor process ever developed and manufactured in the United States. Powering over 200 PC designs: Series 3 delivers a robust family of processors powering hundreds of designs up and down the stack, all delivering exceptional performance, graphics and battery life. From PC to Edge: For the first time, Series 3 processors are tested and certified for embedded and industrial use cases at the edge like robotics, smart cities, automation, healthcare, and more. Series 3 Adds a New Class of Intel Core Ultra X9 and X7 Processors Within the Intel Core Ultra Series 3 mobile lineup, a new class of Intel Core Ultra X9 and